

SEMICONDUCTOR DEVICE

Patent Number: JP1071162
Publication date: 1989-03-16
Inventor(s): WATANABE MASAYUKI; others: 02
Applicant(s): HITACHI LTD; others: 01
Requested Patent: ☐ JP1071162
Application Number: JP19870226307 19870911
Priority Number(s):
IPC Classification: H01L23/52 ; H01L21/60
EC Classification:
Equivalents: JP2642359B2

Abstract

PURPOSE: To assure high density packaging together with the improvement of reliability by superimposing on a substrate two or more of tape carrier packages, each of which is modified to realize the superimposed packaging of tape carrier packages.

CONSTITUTION: A upper tape carrier package 8a is one having a lead pattern 2 shown by A and a lower tape carrier package 8b is one having a lead pattern 2 shown by B. In A, a upper right end leads 2a are disposed in parallel to the remaining leads 2b. In B, the upper right end leads 2a are bent at a right angle. the packages 8a, 8b are superimposed on a packaging substrate 9, for packaging thereof. This improves packaging density compared with a situation where the packages 8a, 8b are provided in parallel to each other. Hereby, reliability is improved.

Data supplied from the esp@canet database - 12